MATERIAL: HOUSING: HIGH TEMP THERMO PLASTIC, UL94V-0
CONTACT: COPPER ALLOY
FINISH: UNDER PL Ni 0.0013mm MIN ALL OVER.
CONTACT AREA: 0.0002mm MIN Au PL.
SOLDERING AREA: SIGNAL POS: 0.00005mm MIN Au PL.
GROUND POS: 0.001mm MIN TiN PL.

THIS POSITION IS GROUND CIRCUIT.
PACKING ASSY DWG SEE SHEET 1.
THIS PRODUCT WAS COATED BY FLUX-PENETRATION.
INHIBITING AGENT.
FINISH: UNDER PL Ni 0.0013mm MIN ALL OVER.
CONTACT AREA: 0.00076mm MIN Au PL.
SOLDERING AREA: SIGNAL POS: 0.00005mm MIN Au PL.
GROUND POS: 0.001mm MIN TiN PL.